

Product Specifications

Part Number ⁶	OCL ¹ (μ H) $\pm 20\%$	FLL ² (μ H) minimum	I_{rms}^3 (A)	I_{sat}^4 (A)	DCR (m Ω) typical @ +20 °C	DCR (m Ω) maximum @ +20 °C	K-factor ⁵
HCM0703-R15-R	0.15	0.09	26	52	1.9	2.5	1044
HCM0703-R22-R	0.22	0.13	23	40	2.5	2.8	986
HCM0703-R47-R	0.47	0.28	17.5	26	4.0	4.2	580
HCM0703-R68-R	0.68	0.41	15.5	25	5.0	5.5	455
HCM0703-R82-R	0.82	0.49	13	24	6.7	8.0	439
HCM0703- 1R0-R	1.0	0.60	11	22	9.0	10	374
HCM0703- 1R5-R	1.5	0.90	9.0	18	14	15	366
HCM0703- 2R2-R	2.2	1.3	8.0	14	18	20	281
HCM0703- 3R3-R	3.3	2.0	6.0	13.5	28	30	252
HCM0703- 4R7-R	4.7	2.8	5.5	10	37	40	210
HCM0703- 6R8-R	6.8	4.1	4.5	8.0	54	60	151
HCM0703- 8R2-R	8.2	4.9	4.0	7.5	64	68	142
HCM0703- 100-R	10	6.0	3.2	7.0	71	78	132
HCM0703- 150-R	14.9 $\pm$ 15%	10.1	2.2	5.0	113	127	105
HCM0703- 220-R	22	14.1	2.3	3.0	135	149	83
HCM0703- 330-R	33	19.8	1.8	2.2	220	242	76

1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25 V_{max}, 0.0 Adc, +25 °C.

2. Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.25 V_{max}, I_{sat} @ +25 °C.

3. I_{DC}: DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents.

PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.

4. I_{sat}: Peak current for approximately 20% rolloff at +25 °C.

5. K-factor: Used to determine B_{pp} for core loss (see graph). B_p-p = K * L * Δ I. B_{pp}: (Gauss), K: (K-factor from table), L: (Inductance in μ H), Δ I (Peak to peak ripple current in Amps).

6. Part Number Definition: HCM0703-xxx-R

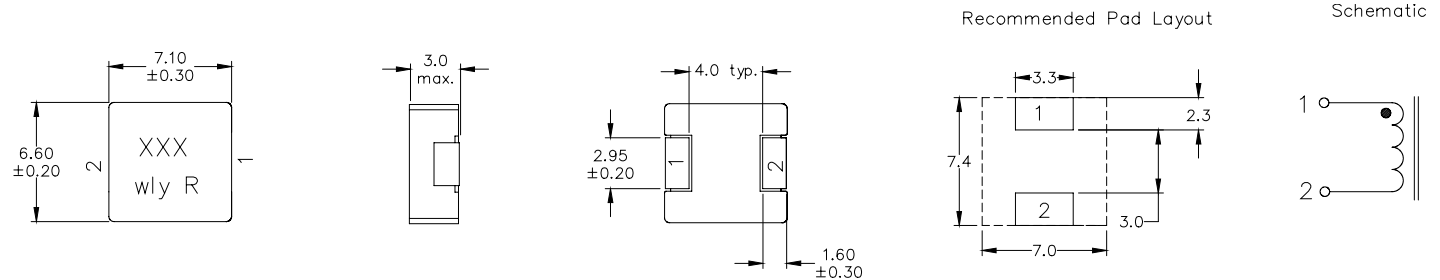
HCM0703 = Product code and size

-xxx= Inductance value in μ H, R = decimal point,

if no R is present then last character equals number of zeros.

"-R" suffix = RoHS compliant

Dimensions (mm)



Part marking: XXX=Inductance value in uH, R= decimal point. If no R is present then last character equals number of zeros.

wly=date code, R=revision level

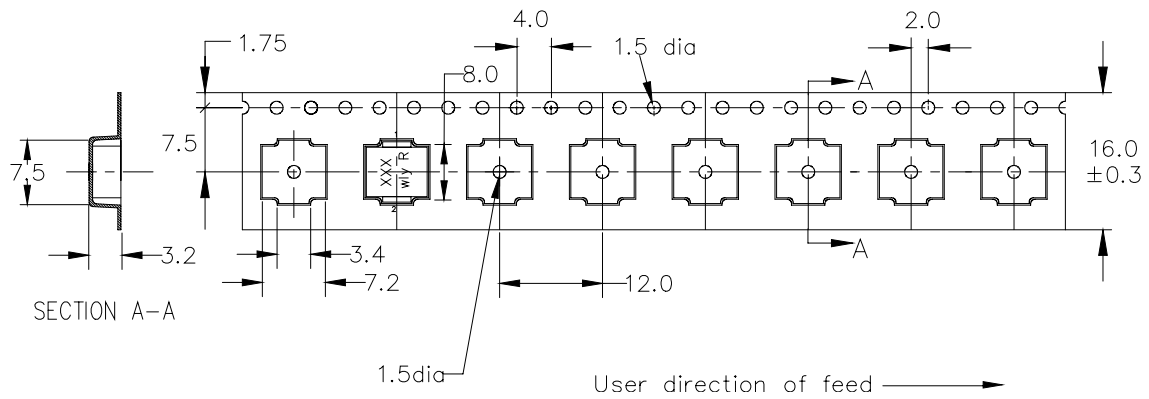
All soldering surfaces to be coplanar within 0.10 millimeters

Tolerances are $\pm$ 0.3 millimeters unless stated otherwise

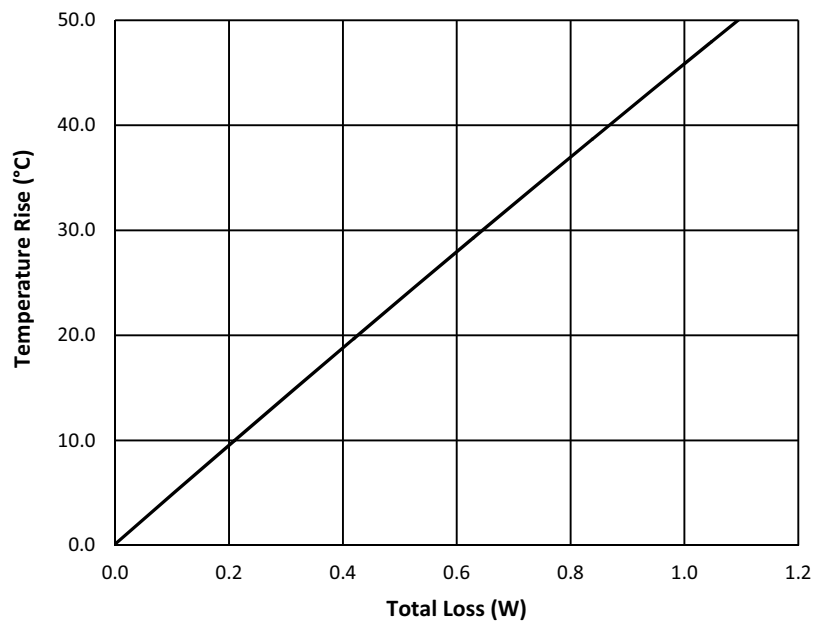
Color: Grey

Packaging information (mm)

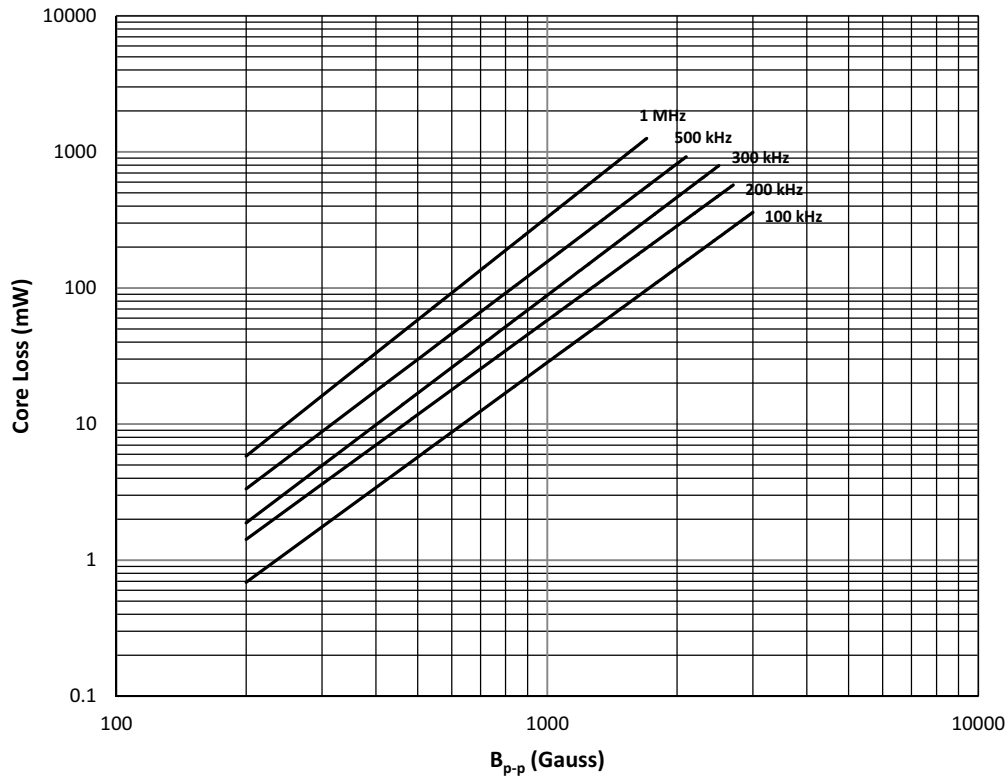
Supplied in tape and reel packaging, 1500 parts per 13" diameter reel.



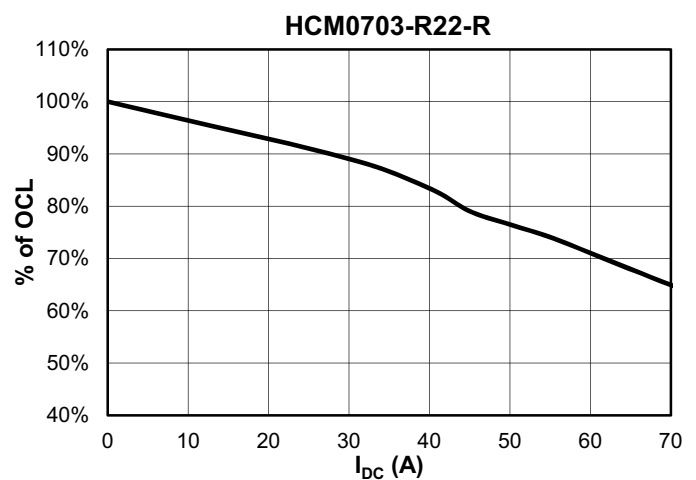
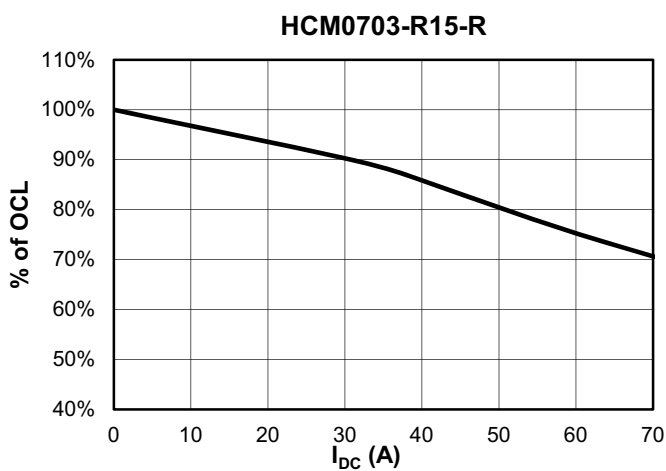
Temperature rise vs. total loss



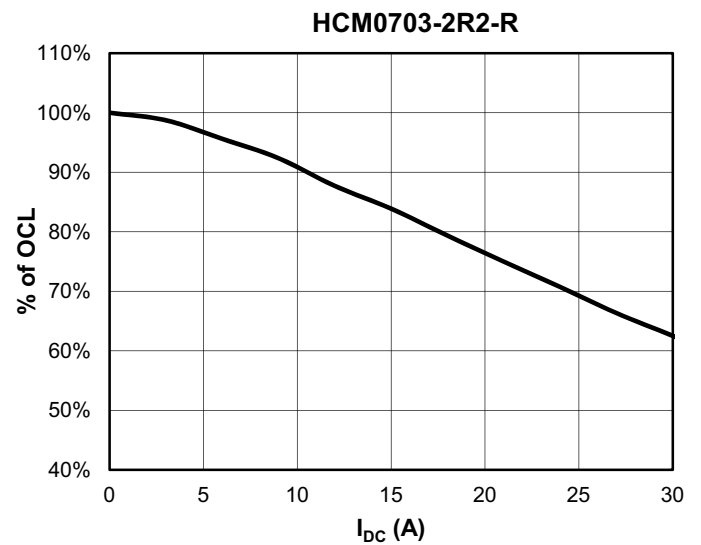
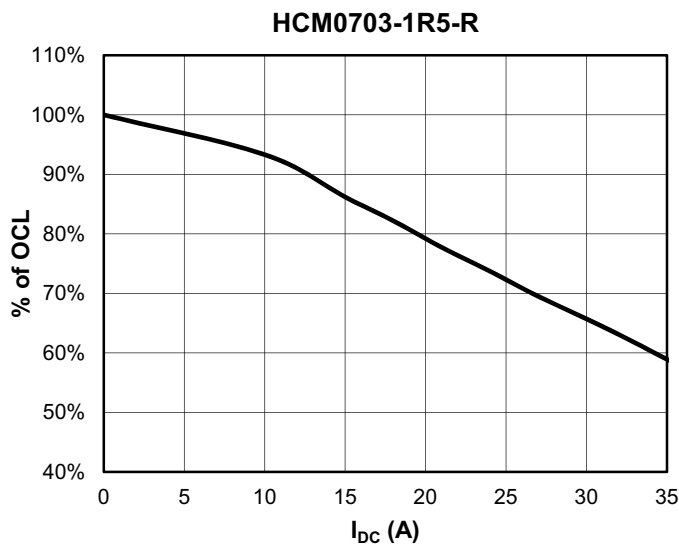
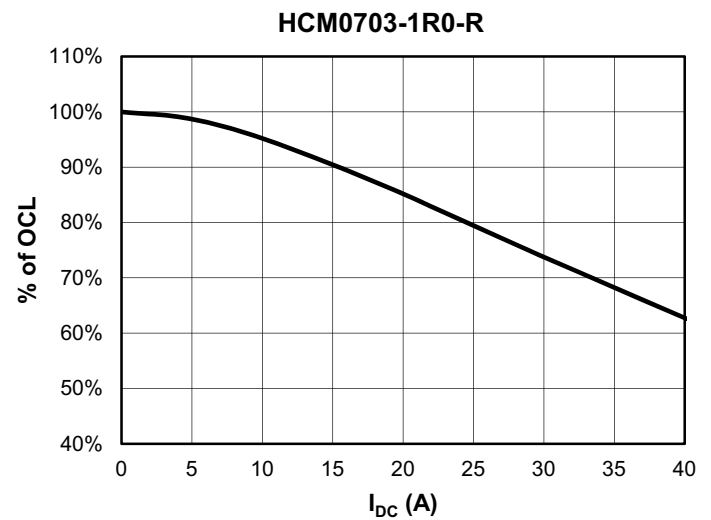
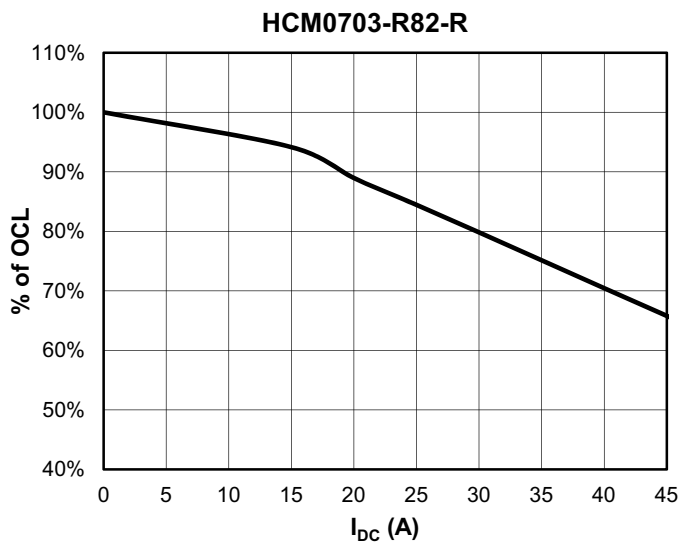
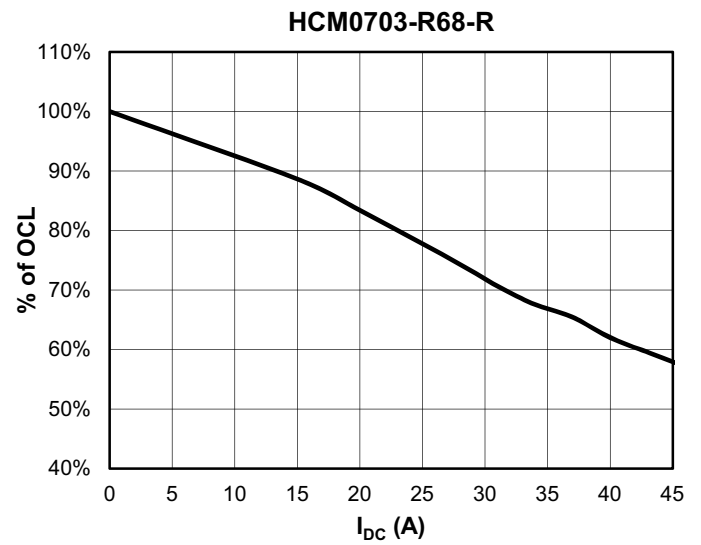
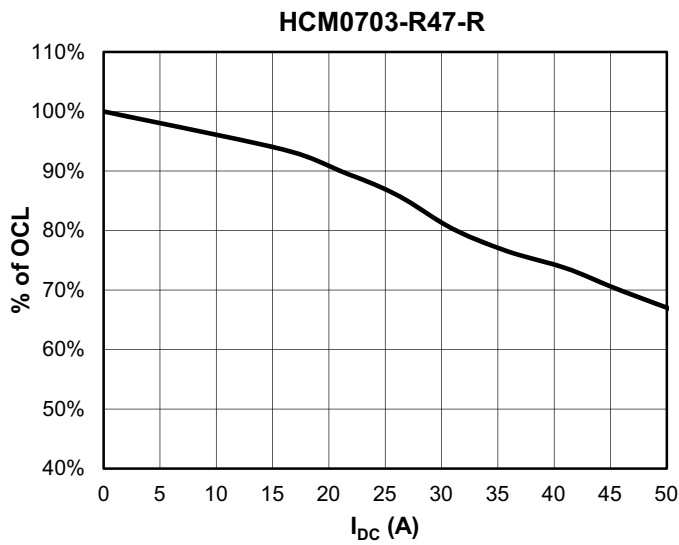
Core loss vs. B_{p-p}



Inductance characteristics

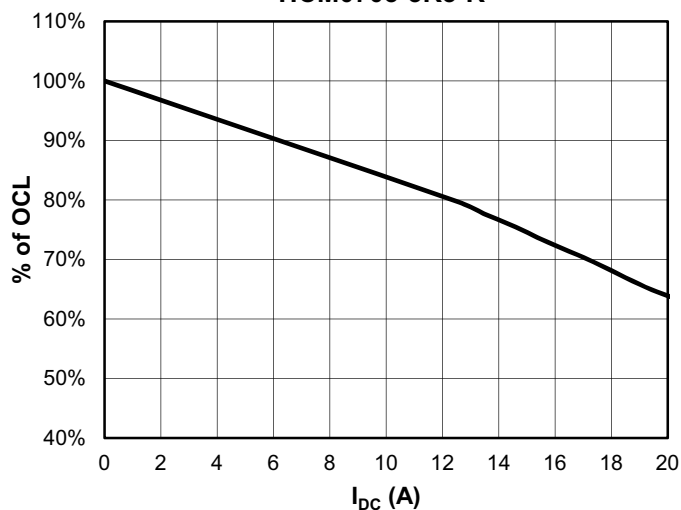


Inductance characteristics

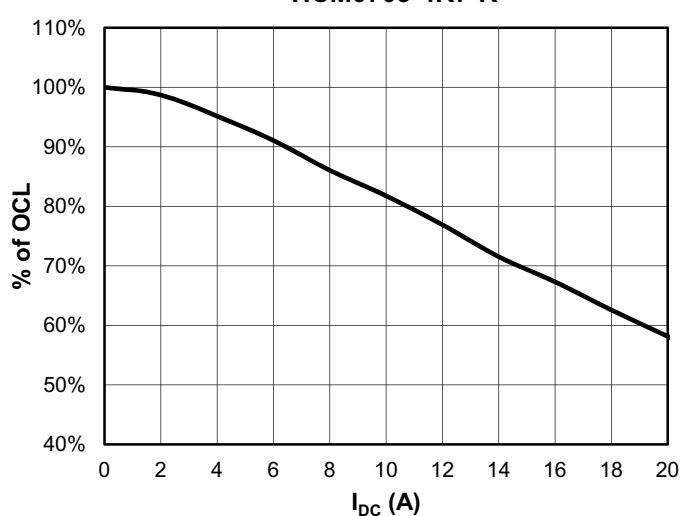


Inductance characteristics

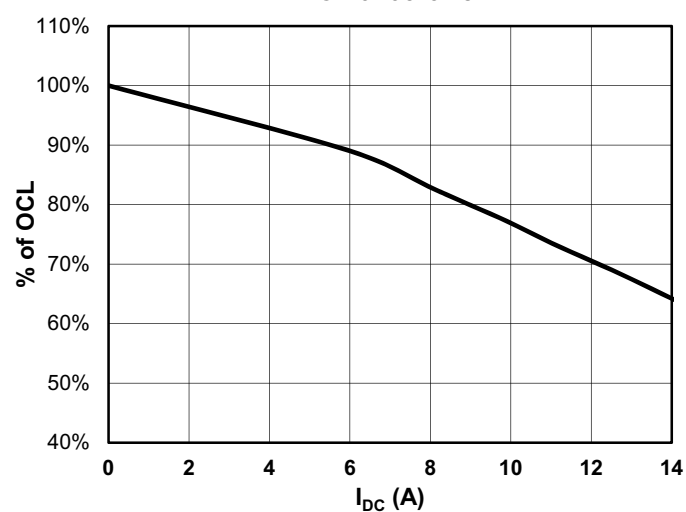
HCM0703-3R3-R



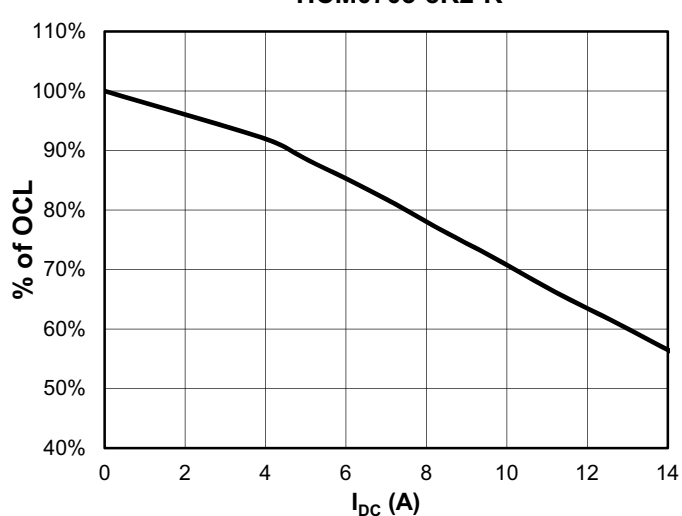
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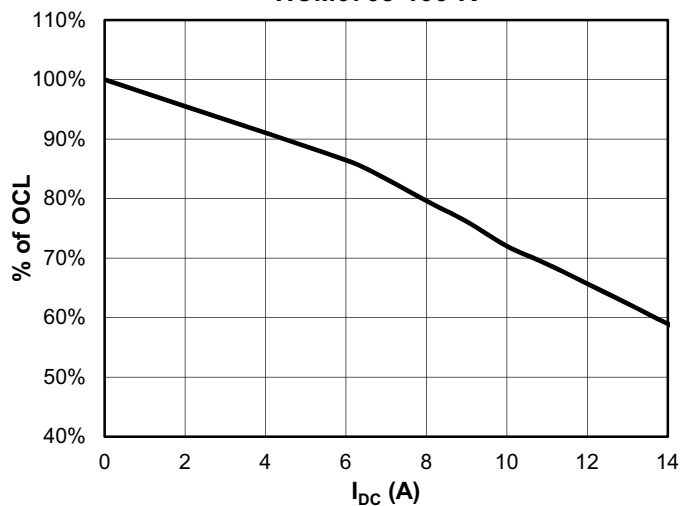
HCM0703-6R8-R



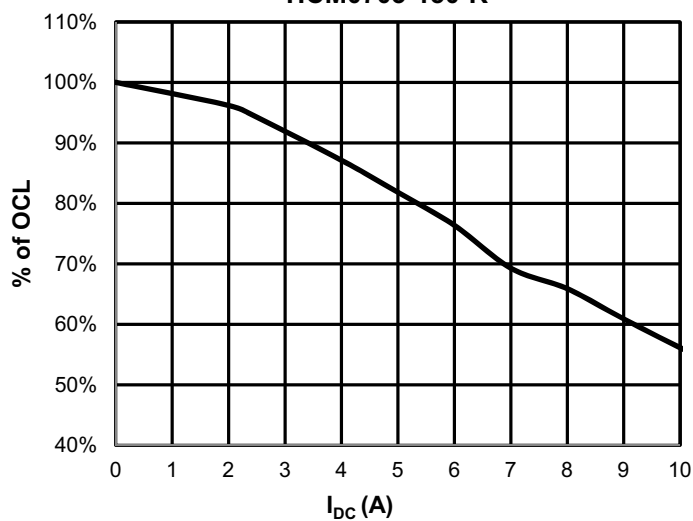
HCM0703-8R2-R



HCM0703-100-R

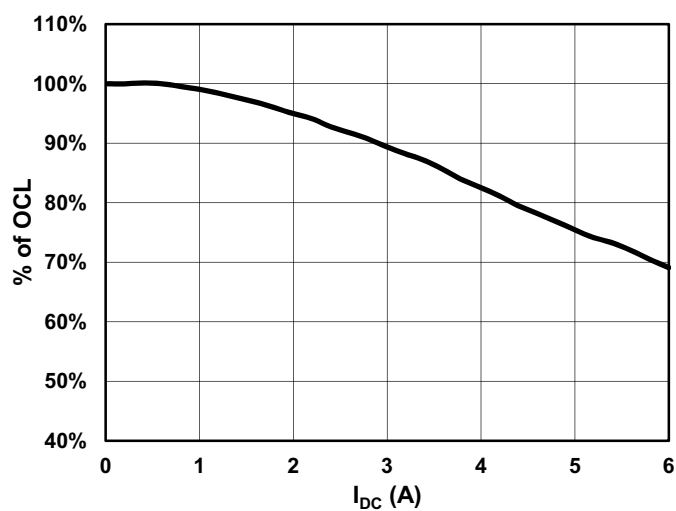


HCM0703-150-R

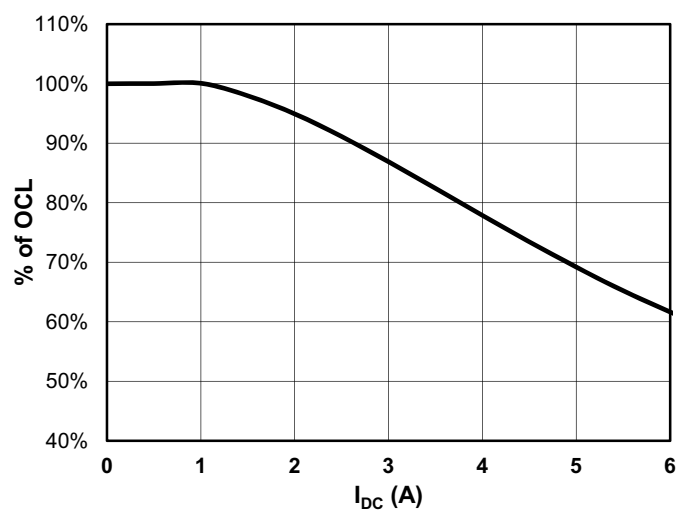


Inductance characteristics

HCM0703-220-R



HCM0703-330-R



Solder reflow profile

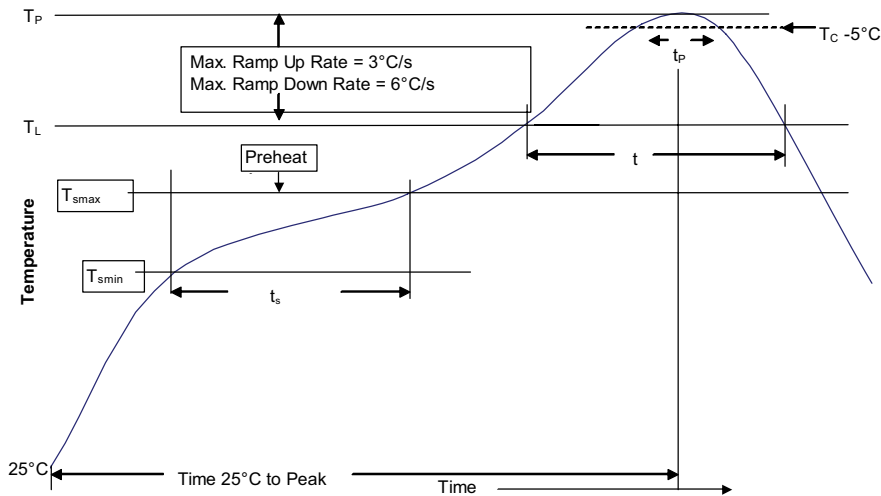


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm)	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Reference JDEC J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100 °C	150 °C
• Temperature max. (T_{smax})	150 °C	200 °C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp up rate T_{smax} to T_P	3 °C/ second Max.	3 °C/ second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body temperature (T_P)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)	20 seconds**	30 seconds**
Average ramp-down rate (T_P to T_{smax})	6 °C/ second Max.	6 °C/ second Max.
Time 25 °C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_P) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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